



DOCKET NO.: EN9-98-122US3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Farquhar *et al.*

Examiner: Goff II, John E

Serial No.: 09/781,730

Art Unit: 1733

Filed: 2/12/01

For: **SEMICONDUCTOR DEVICE HAVING A THERMOSET-CONTAINING DIELECTRIC MATERIAL AND METHODS FOR FABRICATING THE SAME**

Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT**

Sir:

In response to the Office Action mailed August 22, 2002, please amend the above-identified application as follows:

**In the Drawings:**

Please revise the drawings in accordance with the Request for Approval of Drawing Corrections attached hereto.

**In the Specification:**

The paragraph beginning on page 19, line 19 is as follows based on the amendment herein:

Fig. 6 shows an integrated circuit chip carrier 22 that includes the coated filled body 9.

The structure of the chip carrier 22 is generally known to those of ordinary skill in the art and

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